

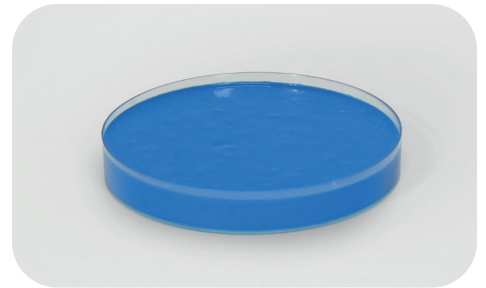
# GFL 3000 SL

## Gap Filler Liquid

# NEW PRELIMINARY DATA SHEET

## Benefits

- Room temperature curing
- Higher thermal conductivity in comparison to potting material
- Usage for Encapsulation, electromagnetic coils and applications with small fabrication tolerances
- High thermal performance
- Low Viscosity Gap Filler Liquid



Properties	Unit	GFL 3000 SL
Colour		steelblue
Basic material		silicone
Mixing ratio		1:1
Curing	°C	1h ; 25 °C
<b>Thermal Properties*</b>		
Thermal resistance $R_{th}$	K/W	0.90
Thermal conductivity $\lambda$	W/mK	2.8
<b>Electrical Properties**</b>		
Dielectric breakdown voltage $U_{d,AC}$	kV	6
<b>Mechanical Properties</b>		
Hardness	Shore 00	15-45
<b>Physical Properties</b>		
Application temperature	°C	-40 to +200
Density	g/cm <sup>3</sup>	2.77
Viscosity	Pas	20-50
Total mass loss (TML)	Ma. -%	< 0.17
Possible thickness	mm	0.2-5.0

\* Measured @ thickness 1 mm \*\* Measured @ thickness 0.5 mm